

WHAT IS CLAIMED IS:

- 1                    1.     A semiconductor device comprising:
  - 2                    a.     a leadframe comprising:
    - 3                    i.       a source pad;
    - 4                    ii.      at least two source lead rails at a periphery of the source pad;
    - 5                    iii.     a gate pad adjacent the source pad and electrically isolated  
6 therefrom; and
    - 7                    iv.      gate lead rail at a periphery of the gate pad;
  - 8                    b.     a die coupled to the source pad and the gate pad; and
  - 9                    c.     a stiffener coupled to the leadframe and electrically isolated therefrom.
- 1                    2.     A semiconductor device in accordance with claim 1 wherein the  
2 stiffener comprises a copper slug.
- 1                    3.     A semiconductor in accordance with claim 1 wherein the stiffener is  
2 coupled to the leadframe with polyimide tape that provides the electrical isolation.
- 1                    4.     A semiconductor device in accordance with claim 2 wherein the  
2 stiffener comprises a copper slug.
- 1                    5.     A semiconductor device in accordance with claim 4 comprising at least  
2 three source lead rails.
- 1                    6.     A method of making a semiconductor device, the method comprising:
  - 2                    providing a leadframe comprising:
    - 3                    a.       a source pad;
    - 4                    b.       at least two source lead rails at a periphery of the source pad;
    - 5                    c.       a gate pad adjacent the source pad and electrically isolated therefrom;  
6 and
    - 7                    d.       a gate lead rail at a periphery of the gate pad;
  - 8                    flipping a bumped die including a plurality of solder bumps onto the source  
9 and gate pads; and
  - 10                    reflowing the solder bumps.
- 1                    7.     A method in accordance with claim 6 further comprising:
  - 2                    performing a laser cut;

3 testing the semiconductor device; and  
4 placing the semiconductor onto tape on a reel.

1 8. A method in accordance with claim 6 wherein the testing comprises  
2 isolating the gate pad and strip testing prior to performing the laser cut.

1 9. A method in accordance with claim 6 further comprising performing  
2 an underfill application and a cure after reflowing the solder bumps.

1 10. A method in accordance with claim 9 wherein the testing comprises  
2 isolating the gate pad and strip testing prior to performing the laser cut.

1 11. A semiconductor device comprising:  
2 a. a leadframe including first and second surfaces;  
3 b. a die coupled to the first surface; and  
4 c. a stiffener coupled to the second surface and electrically isolated  
5 therefrom.

1 12. A semiconductor device in accordance with claim 11 wherein the  
2 stiffener is coupled to the leadframe with polyamide tape that provides the electrical isolation.

1 13. A semiconductor device in accordance with claim 11 wherein the  
2 stiffener comprises a copper slug.

1 14. A method of making a semiconductor device, the method comprising:  
2 providing a leadframe including a first surface and a second surface;  
3 coupling a die to the first surface with solder; and  
4 reflowing the solder.